

A

**Pin heatsinks**

B

C

D

E

F

G

H

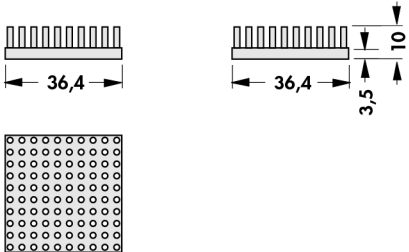
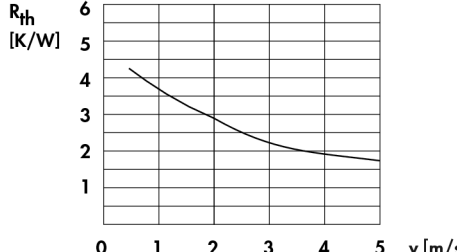
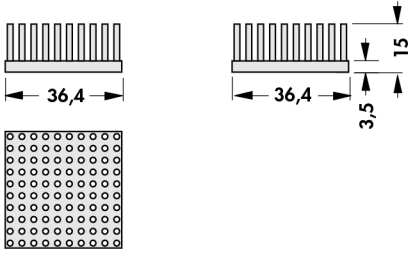
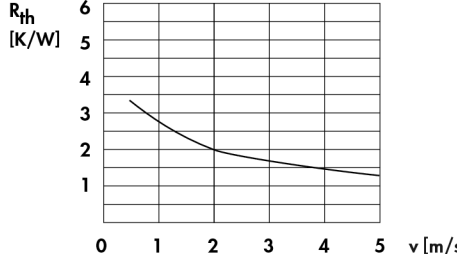
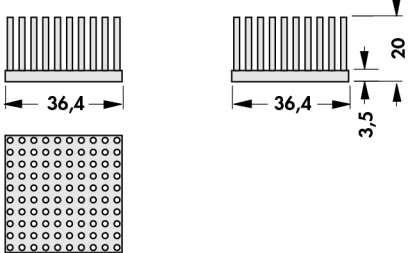
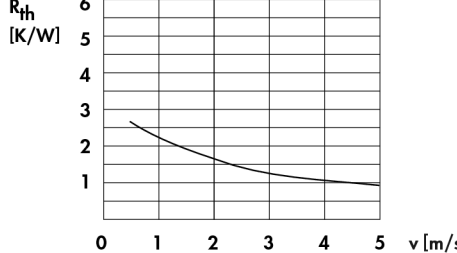
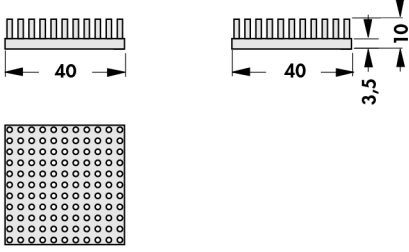
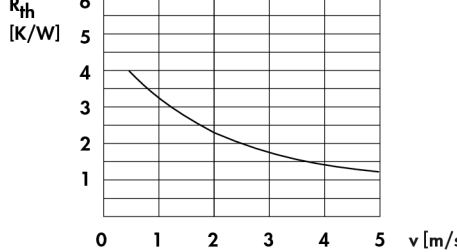
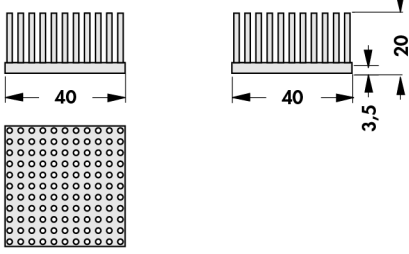
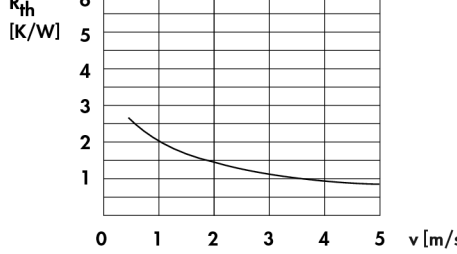
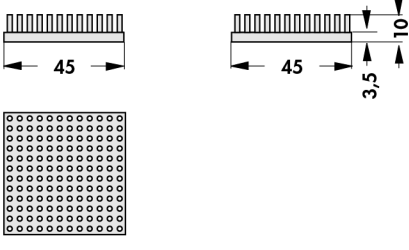
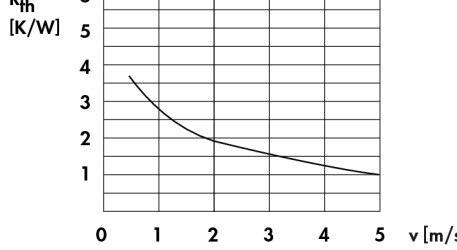
I

K

L

M

N

<b>art. no.</b>  <b>ICK S 36 x 36 x 10</b> WLF ... 36 x 36 weight: 17 g		
<b>art. no.</b>  <b>ICK S 36 x 36 x 15</b> WLF ... 36 x 36 weight: 20 g		
<b>art. no.</b>  <b>ICK S 36 x 36 x 20</b> WLF ... 36 x 36 weight: 24 g		
<b>art. no.</b>  <b>ICK S 40 x 40 x 10</b> WLF ... 40 x 40 weight: 21 g		
<b>art. no.</b>  <b>ICK S 40 x 40 x 20</b> WLF ... 40 x 40 weight: 29 g		
<b>art. no.</b>  <b>ICK S 45 x 45 x 10</b> WLF ... 45 x 45 weight: 26 g		

**B 19**

Thermal conduct. foil WLFT 404/405 → E 5  
 Thermal conductive glue → E 14  
 Thermal conductive paste → E 12  
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27  
 Mounting material for semiconduct. → E 34 - 38  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7